

**APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	<b>THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD</b>		
Application Type: regular, utility			
Attorney Docket Number: 27-017			
Correspondence address:			
Customer Number:		22898	*22898*
Inventors Information:			
<u>Inventor 1:</u>			
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State of Mailing Address:			
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**Inventor 2:**

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**Publication Information:**

**Suggested Figure for Publication – FIG 4**

**Suggested Classification –**

**Suggested Technology Center –**

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**Assignee 1:**

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